

Technical Data
Data Sheet N1166, Rev. -

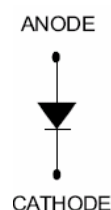
126NQ200-1 SCHOTTKY RECTIFIER

Applications:

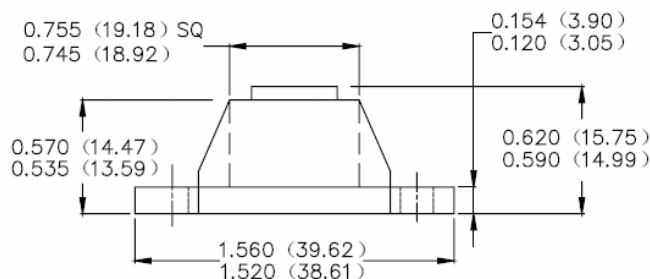
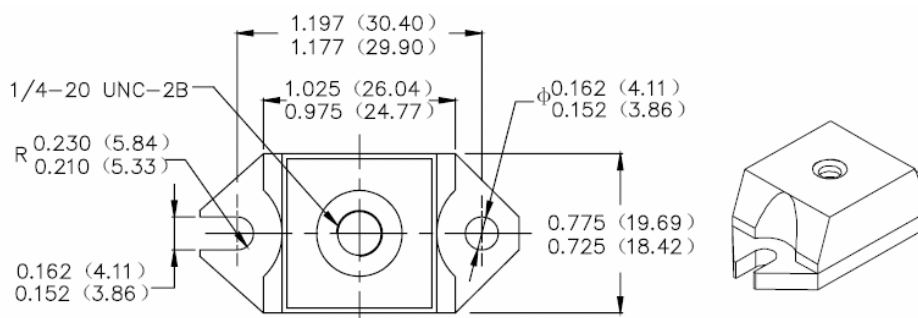
- Switching power supply • Converters • Free-Wheeling diodes • Reverse battery protection

Features:

- 175°C T_J operation
- Unique high power, Half-Pak module
- Replaces three parallel DO-5'S
- Easier to mount and lower profile than DO-5'S
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request



Mechanical Dimensions: In Inches / mm



PRM1-1(HALF PAK Module)

MARKING, MOLDING RESIN

Marking for 126NQ200-1, 1st row SS YYWWL, 2nd row 126NQ200-1

Where YY is the manufacture year

WW is the manufacture week code

L is the wafer's Lot Number

Molding resin

Epoxy resin UL:94V-0

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Green Products
Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	V_{RWM}	-	200	V
Average Forward Current	$I_{F(AV)}$	50% duty cycle @ $T_C=110^{\circ}C$, rectangular wave form	120	A
Peak One Cycle Non-Repetitive Surge Current (per leg)	I_{FSM}	8.3 ms, half Sine pulse	2500	A

Electrical Characteristics:

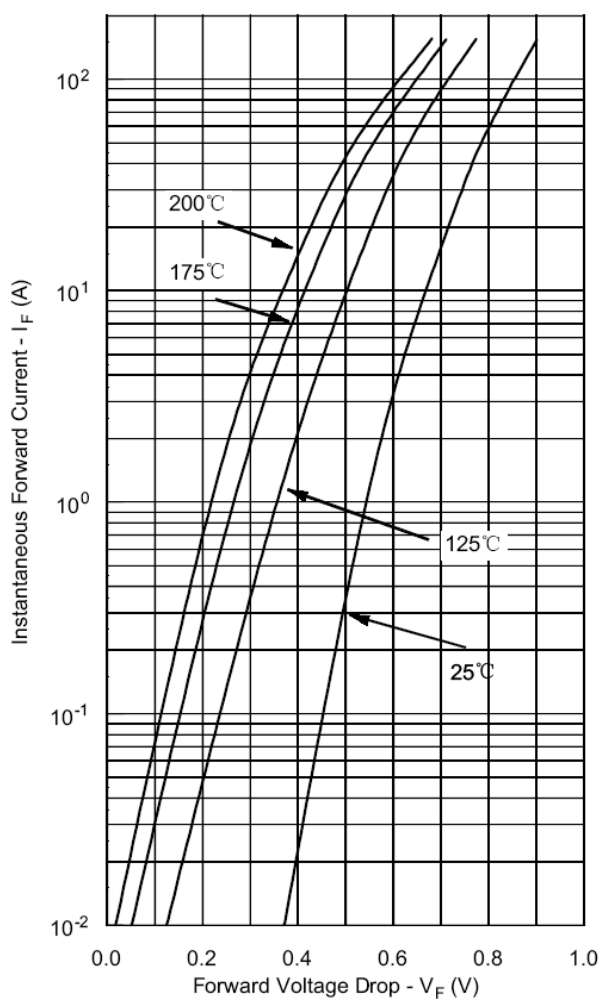
Characteristics	Symbol	Condition	Max.	Units
Forward Voltage Drop*	V_{F1}	@ 120A, Pulse, $T_J = 25^{\circ}C$	1.12	V
	V_{F2}	@ 120A, Pulse, $T_J = 125^{\circ}C$	0.79	V
Reverse Current (per leg) *	I_{R1}	@ $V_R = \text{rated } V_R$ $T_J = 25^{\circ}C$	3	mA
	I_{R2}	@ $V_R = \text{rated } V_R$ $T_J = 125^{\circ}C$	45	mA
Junction Capacitance (per leg)	C_T	@ $V_R = 5V$, $T_C = 25^{\circ}C$ $f_{SIG} = 1MHz$	1800	pF
Typical Series Inductance (per leg)	L_S	Measured lead to lead 5 mm from package body	6.0	nH
Voltage Rate of Change	dv/dt	-	10,000	V/ μs

- Pulse Width < 300 μs , Duty Cycle <2%

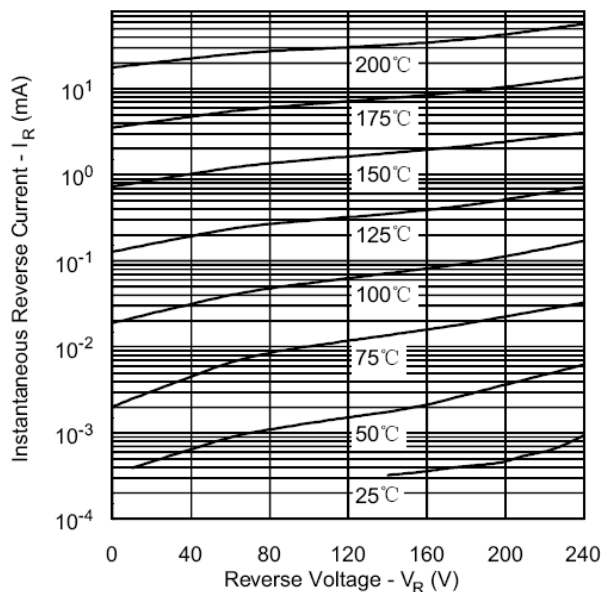
Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units	
Max. Junction Temperature	T_J	-	-55 to +175	$^{\circ}C$	
Max. Storage Temperature	T_{stg}	-	-55 to +175	$^{\circ}C$	
Maximum Thermal Resistance Junction to Case	$R_{\theta JC}$	DC operation	0.40	$^{\circ}C/W$	
Typical Thermal Resistance, case to Heat Sink	$R_{\theta cs}$	Mounting surface, smooth and greased	0.15	$^{\circ}C/W$	
Mounting Torque	T_M	Non-lubricated threads	Mounting Torque	23(min) 29(max)	Kg-cm
			Terminal Torque	35(min) 46(max)	
Approximate Weight	wt	-	25.6	g	
Case Style	PRM1-1				

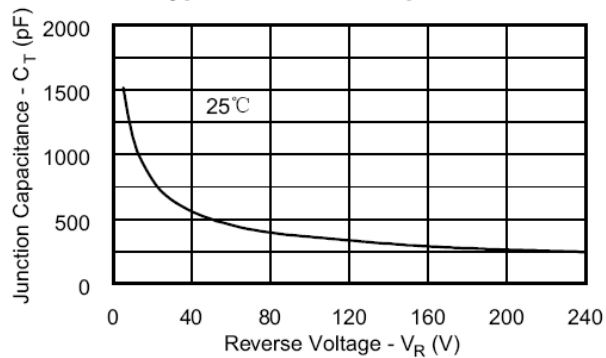
Typical Forward Characteristics



Typical Reverse Characteristics



Typical Junction Capacitance



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